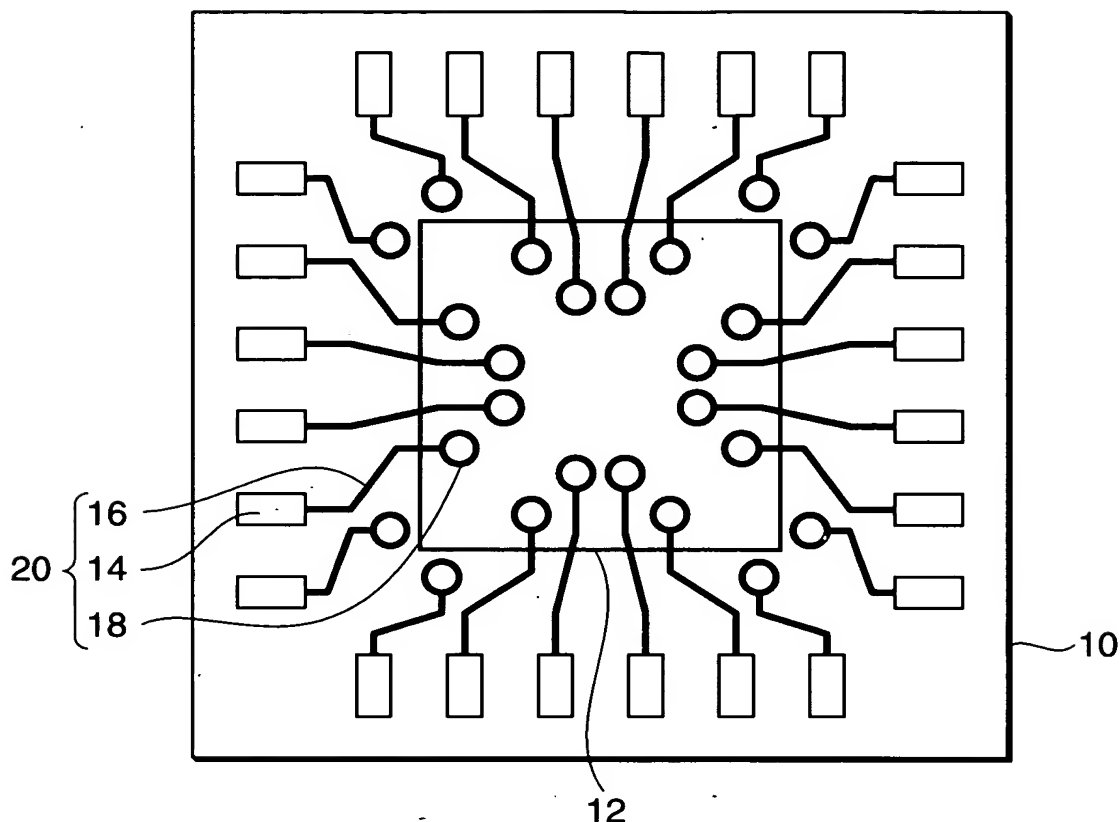


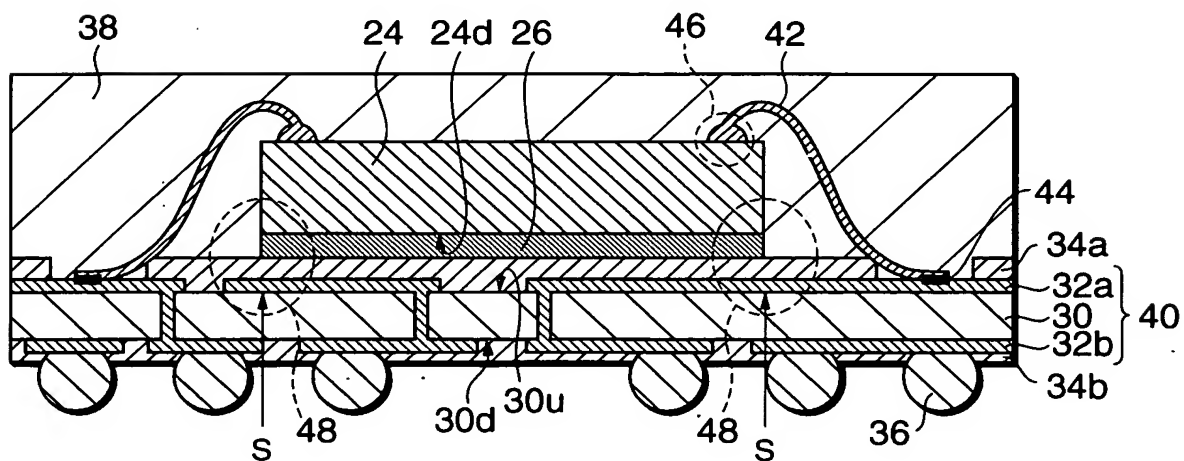
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Fig. 1



PLAN VIEW OF SEMICONDUCTOR DEVICE HAVING
CONVENTIONAL BGA PACKAGE STRUCTURE

Fig. 2



CROSS-SECTIONAL VIEW OF SEMICONDUCTOR DEVICE HAVING CONVENTIONAL BGA PACKAGE STRUCTURE

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Fig. 5A

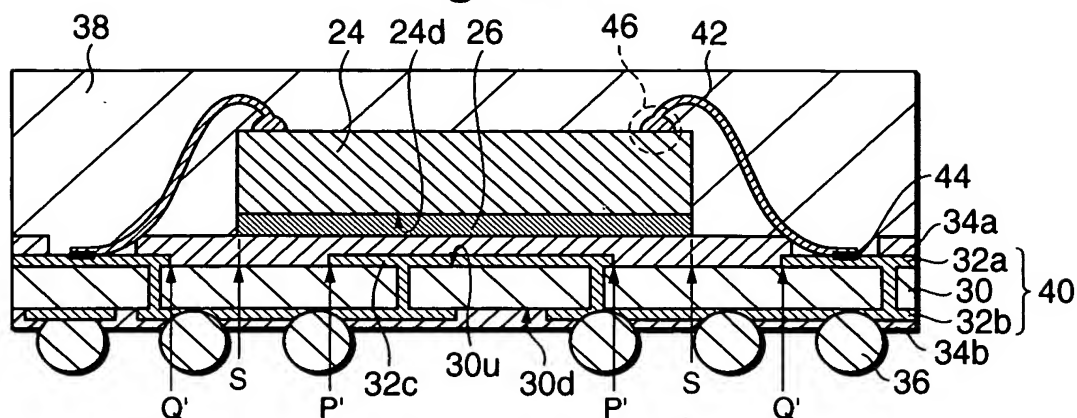
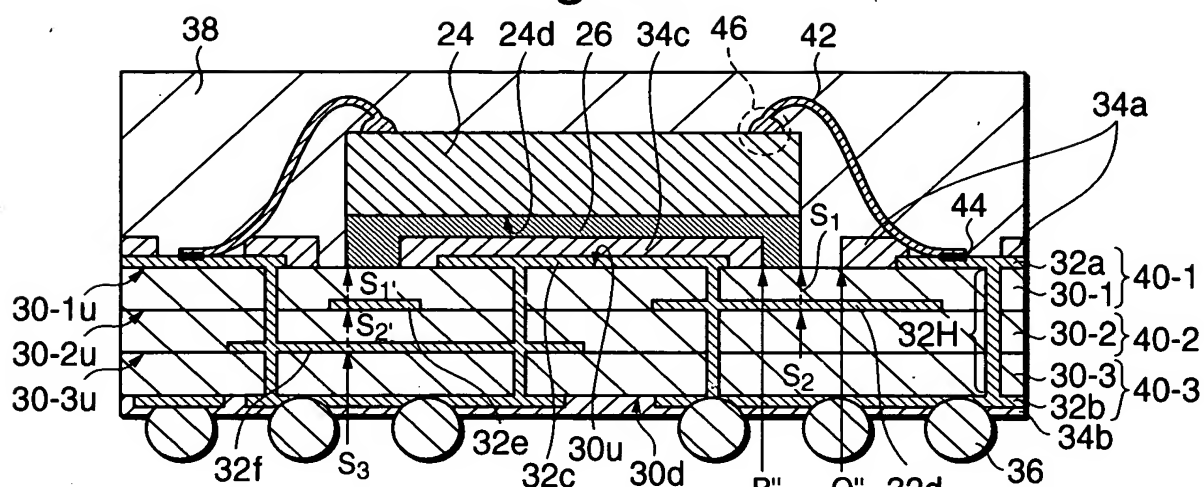
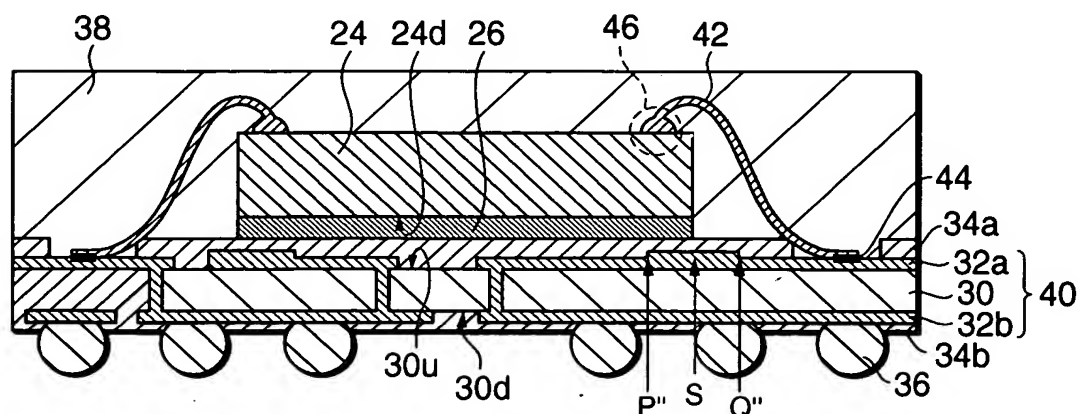


Fig. 5B



CROSS-SECTIONAL VIEW OF SEMICONDUCTOR DEVICE ACCORDING TO SECOND EMBODIMENT

Fig. 6



**CROSS-SECTIONAL VIEW OF SEMICONDUCTOR DEVICE
ACCORDING TO THIRD EMBODIMENT**

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Fig. 7A

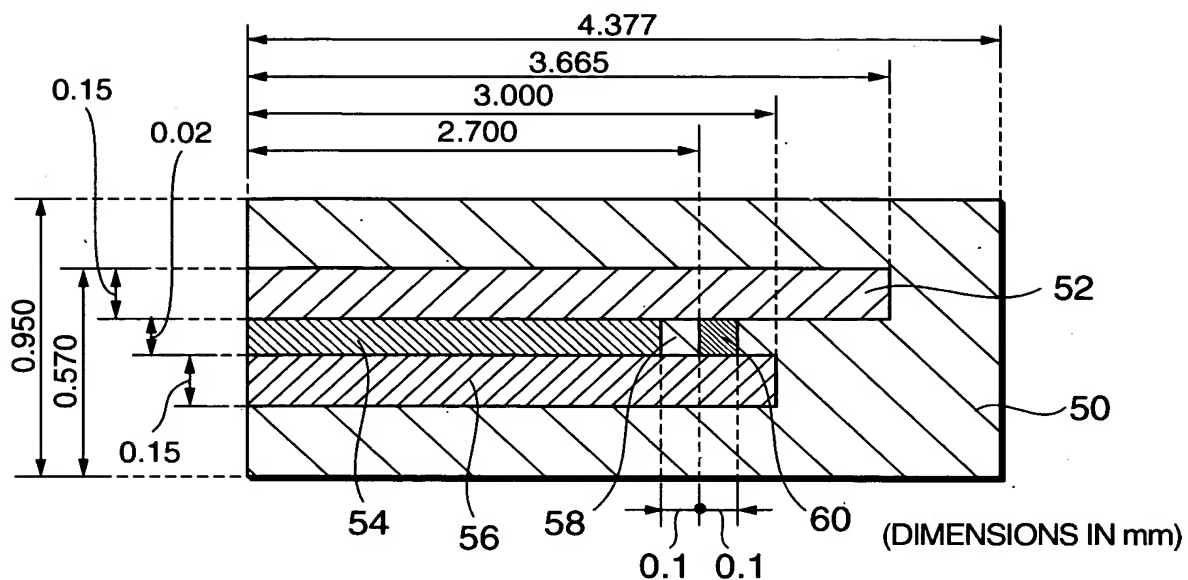


Fig. 7B

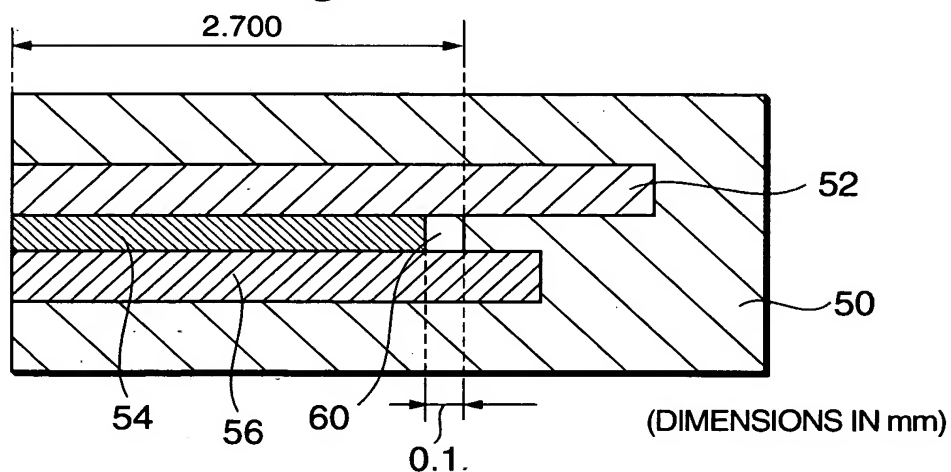
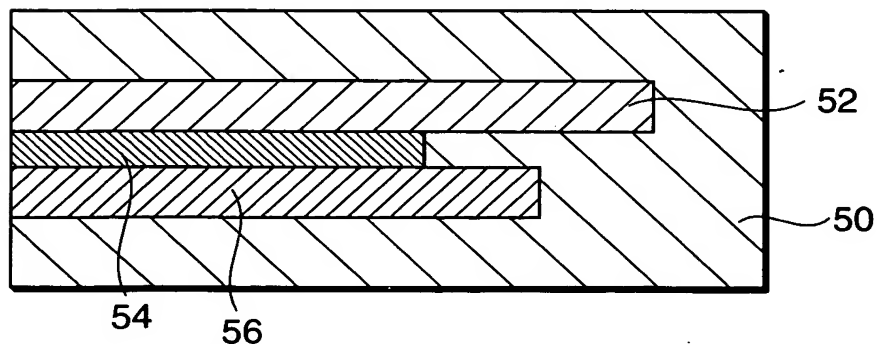


Fig. 7C



SCHEMATIC CROSS-SECTIONAL VIEW OF QUASI SEMICONDUCTOR DEVICE